

Dimensions in mm

Reference Jedec MO-192

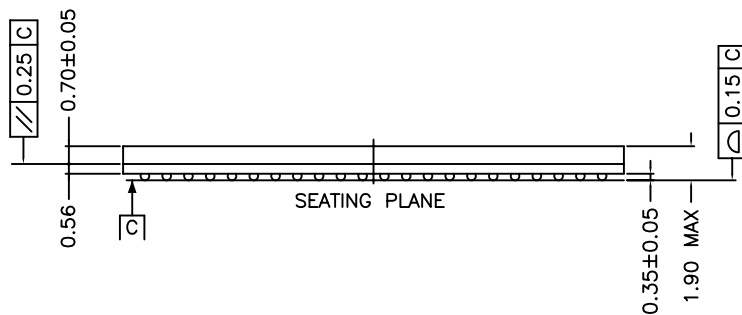
Package Weight – Refer to PMDD spec

TOP VIEW

A1 CORNER

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22

A
B
C
D
E
F
G
H
J
K
L
M
N
P
R
T
U
V
W
Y
AA
AB



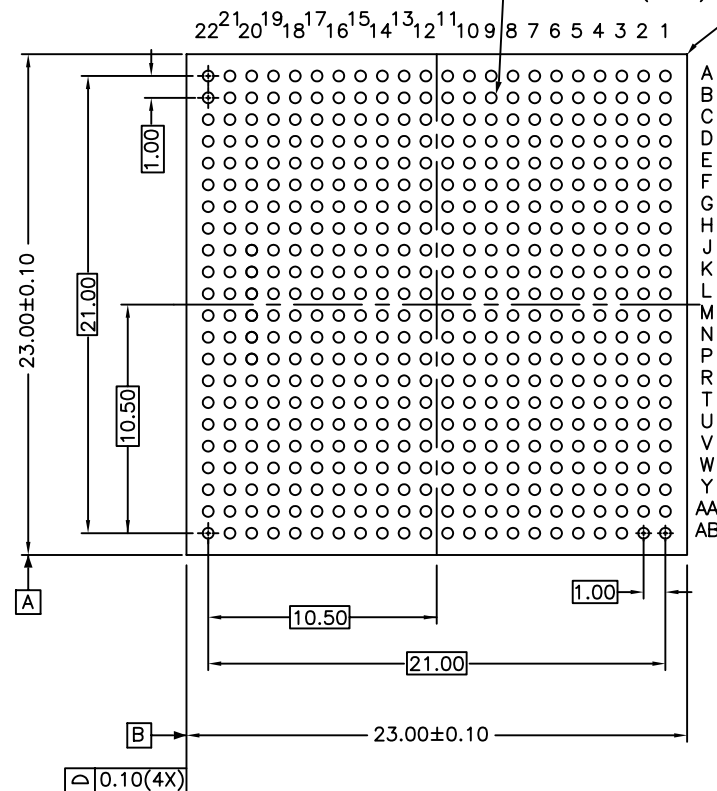
REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	101258	NEW RELEASE	05/25/00	N/A
1	-	*A	106856	CHG. DIM. ON BALL HEIGHT & FLATNESS TOL.	05/01/01	N/A
1	-	*B	115630	CHG. DIM. ON BALL HEIGHT/ADD SUBSTRATE DIM./ADD MOLD CAP DIM.	05/14/02	N/A
1	-	*C	127000	CORRECT LEAD COPLANARITY DIM. TO 0.15	05/14/03	N/A
1	-	*D	128700	CHG. BALL SIZE, BALL HEIGHT, LEAD COPLANARITY AND TOTAL PKG. HEIGHT/ ADD JEDEC NO./ CHANGE TITLE.	07/23/03	N/A
1	-	*E	360958	Flatness changes to 0.15. Add pkg weight.	05/06/05	N/A
1	-	*F	2758054	Change ball diameter and height. Update drawing to new format.	08/31/09	N/A
1	-	*G	2813799	Changed to a standard template.	11/27/09	QAD
1	-	*H	3353048	Update spec for Sunset Review, no change.	08/24/11	QAD
1	-	*I	3726298	Changed package weight reference from 1.3grams to "refer to PMDD spec"	08/28/12	QAD


BOTTOM VIEW

Ø0.05	M	C
Ø0.25	M	C

A1 CORNER

Ø0.45±0.05(484X)



UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON: DECIMALS .XX ± 0.05 .XXX ± .XXXX + ANGLES ± 1°		DESIGNED BY M.L.A.	DATE 08/31/09	 CYPRESS Company Confidential		
		DRAWN BY M.L.A.	DATE 08/31/09			
		CHECKED BY XANC	DATE 08/28/12	TITLE PACKAGE OUTLINE, 484L FBGA 23X23X1.9 MM BB484		
		APPROVED BY QAD	DATE 08/28/12			
MATERIAL N/A	APPROVED BY EDCA	DATE 08/28/12	SIZE A	PART NO. BB484	DWG NO 51-85124	REV *
FINISH N/A	APPROVED BY PRC	DATE 08/28/12	SCALED TO FIT		N/A	SHEET 1 OF 1

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